

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [1052] with the following amended paragraph:

[1052] Referring to FIG 5B, another exemplary integrated circuit die cross-section 550 illustrates a Faraday cage surrounding an inductor structure (i.e., inductor 525). Top plate ~~[[552]]~~ 553 is formed in a redistribution layer by, e.g., under bump metallurgy. Sidewalls 556 and 550 are formed in redistribution layers. Rows of vias in the typical integrated circuit layers, e.g., rows 564 and 562, are electrically coupled to sidewalls 556 and 550.